

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ °C}$)

Symbol	Parameter	Value	Unit
V_{PP}	Peak pulse voltage: IEC 61000-4-2 contact discharge IEC 61000-4-2 air discharge	8 20	kV
P_{PP}	Peak pulse power (8/20 μ s)	30	W
I_{PP}	Peak pulse current (8/20 μ s)	1	A
T_j	Operating junction temperature range	- 40 to +150	°C
T_{stg}	Storage temperature range	- 65 to +150	°C
T_L	Maximum lead temperature for soldering during 10 s	260	°C

Note: For a surge greater than the maximum values, the diode will fail in short-circuit

Figure 2. Electrical characteristics (definitions)

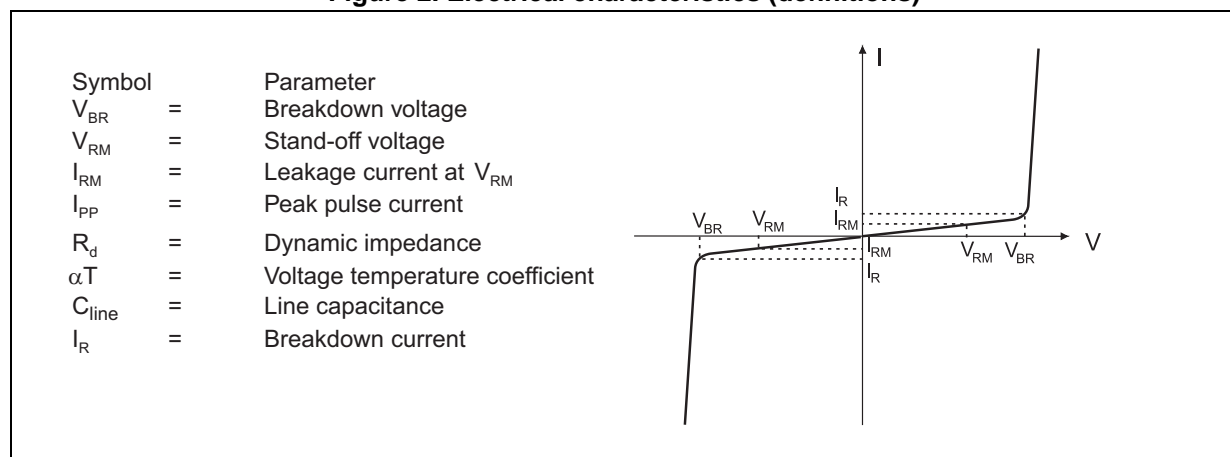


Table 2. Electrical characteristics (values, $T_{amb} = 25\text{ °C}$)

Symbol	Test Condition	Min.	Typ.	Max.	Unit
V_{BR}	$I_R = 1\text{ mA}$	6			V
I_{RM}	$V_{RM} = 3\text{ V}$		1	70	nA
V_{CL}	$I_{PP} = 1\text{ A}$, 8/20 μ A			30	V
C_{line}	$F = (200\text{ MHz} - 3000\text{ MHz})$, $V_R = 0\text{ V}$		0.24	0.35	pF

Figure 3. Leakage current versus junction temperature (typical values)

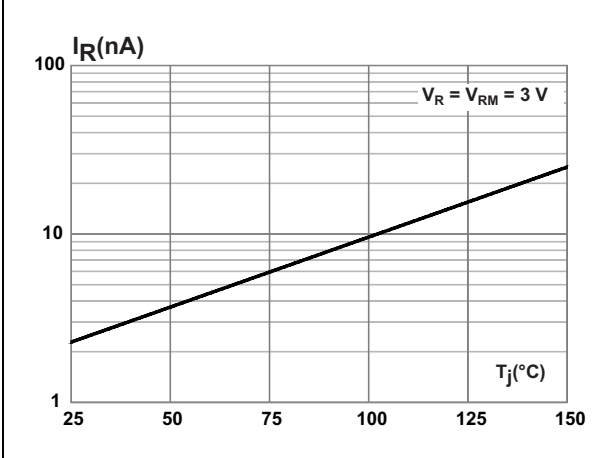


Figure 4. Junction capacitance versus applied voltage (typical values)

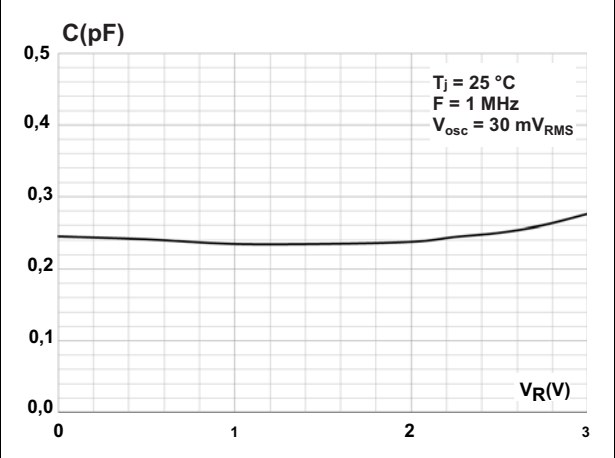


Figure 5. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

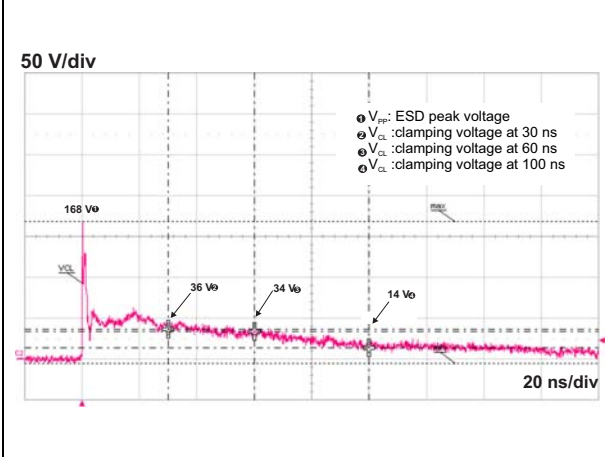


Figure 6. ESD response to IEC 61000-4-2 (-8 kV contact discharge)

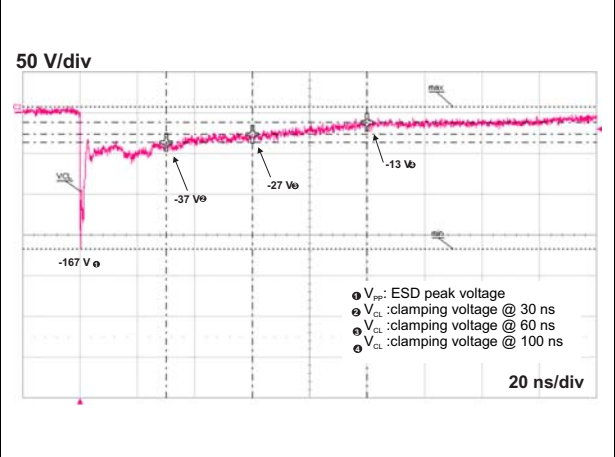
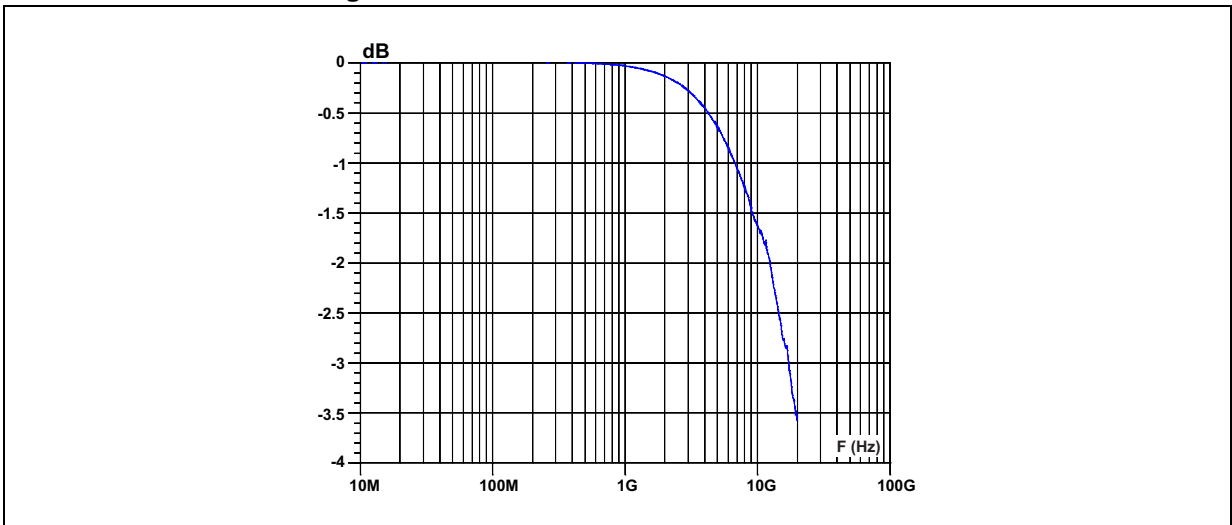


Figure 7. S21 attenuation measurement results



2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

2.1 ST0201 package information

Figure 8. ST0201 package outline

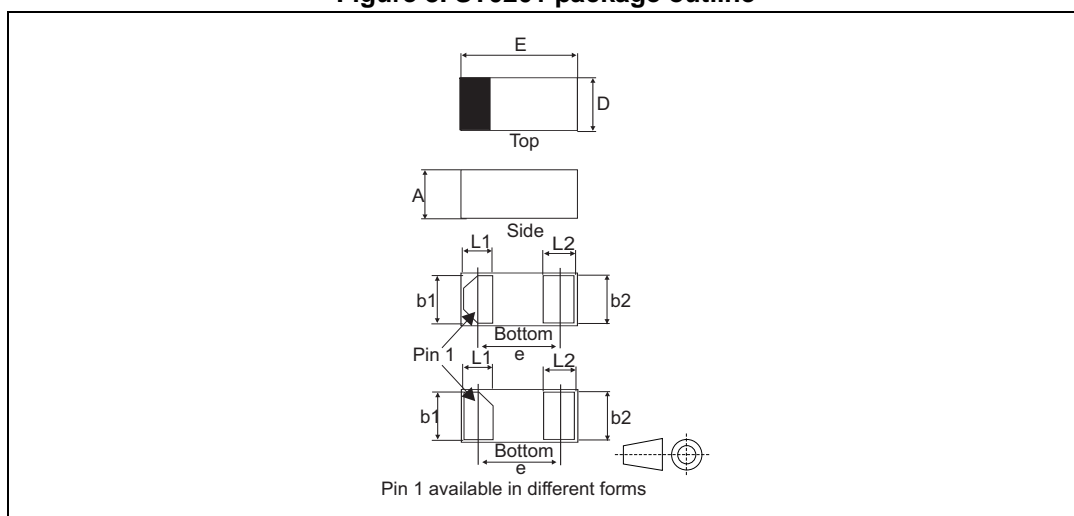


Table 3. 0201 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.23	0.28	0.33	0.0091	0.0110	0.0130
b1	0.20	0.25	0.30	0.0079	0.0098	0.0118
b2	0.20	0.25	0.30	0.0079	0.0098	0.0118
D	0.25	0.30	0.35	0.0099	0.0118	0.0138
E	0.55	0.60	0.65	0.0217	0.0236	0.0256
e		0.35			0.0138	
L1	0.13	0.18	0.23	0.0052	0.0071	0.0091
L2	0.14	0.19	0.24	0.0055	0.0075	0.0095

2.2 Packing information

Figure 9. Footprint, dimensions in mm (inches)

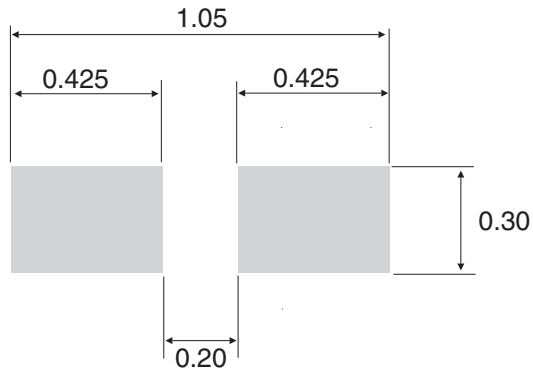
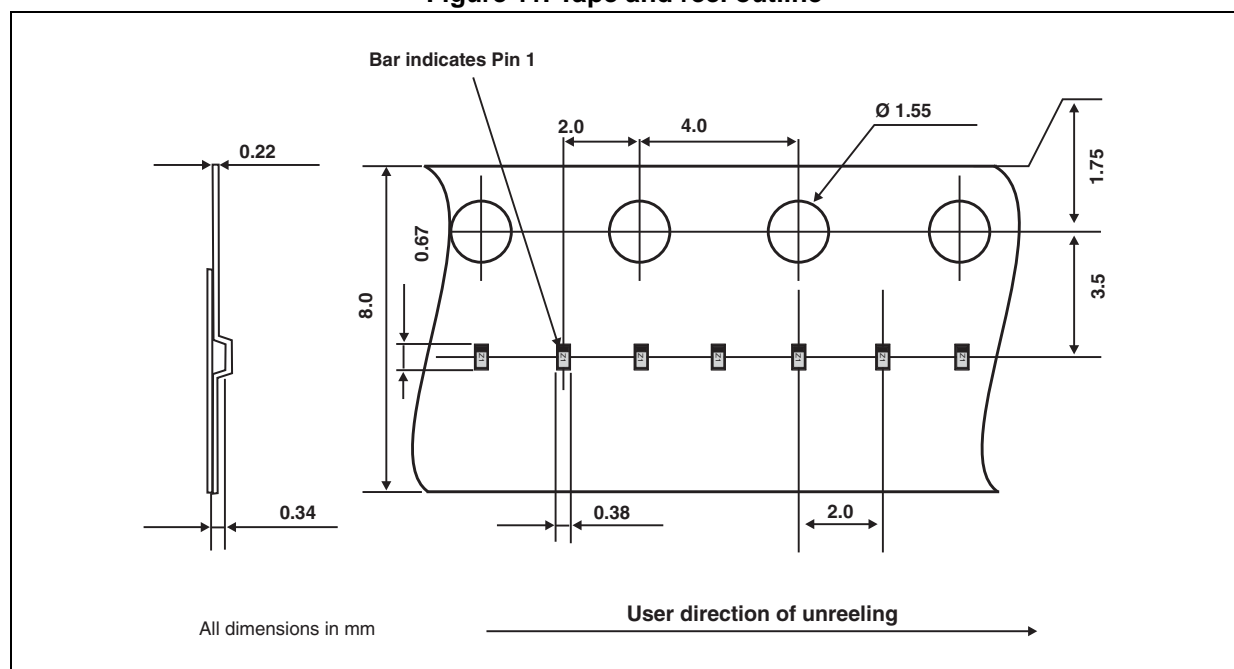


Figure 10. Marking



Note: Product marking may be rotated by 180° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

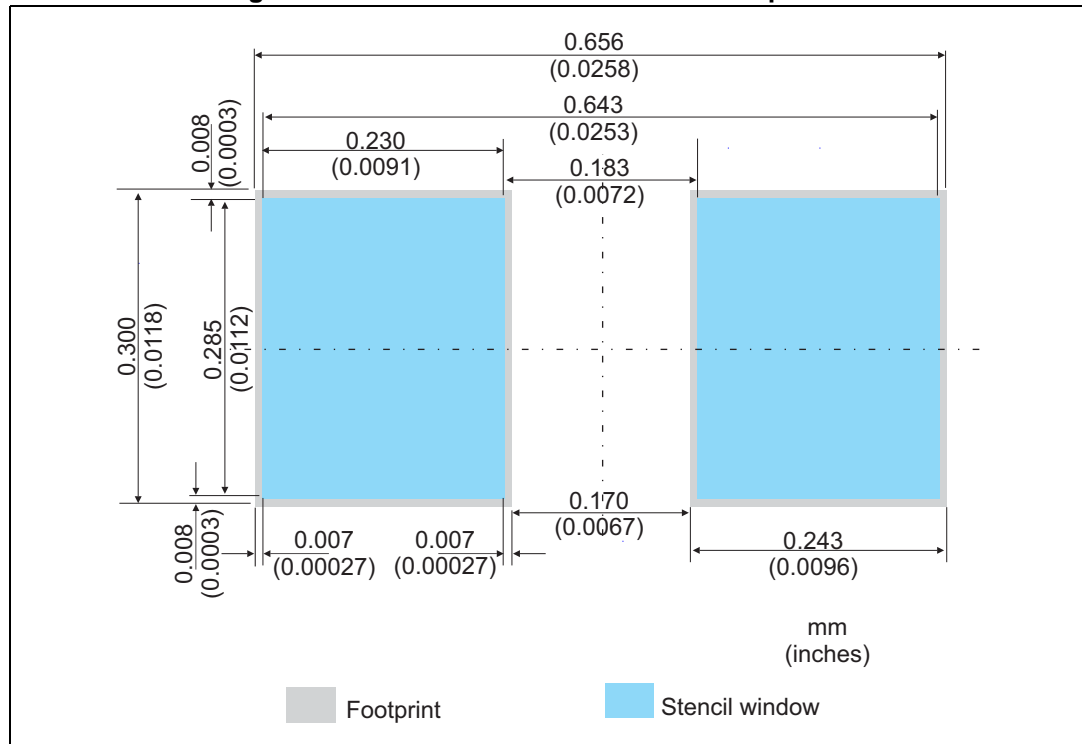
Figure 11. Tape and reel outline



3 Recommendation on PCB assembly

3.1 Stencil opening design

Figure 12. Recommended stencil windows position



3.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. "No clean" solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed
4. Solder paste with fine particles: powder particle size is 20-45 μm .

3.3 Placement

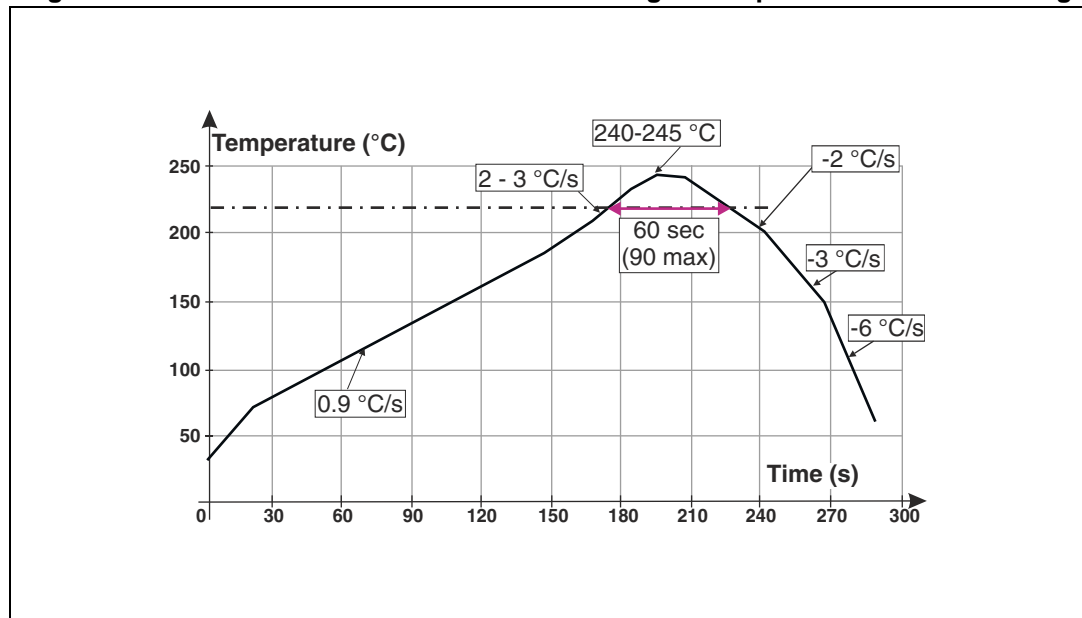
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of ± 0.05 mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

3.5 Reflow profile

Figure 13. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.

4 Ordering information

Figure 14. Ordering information scheme

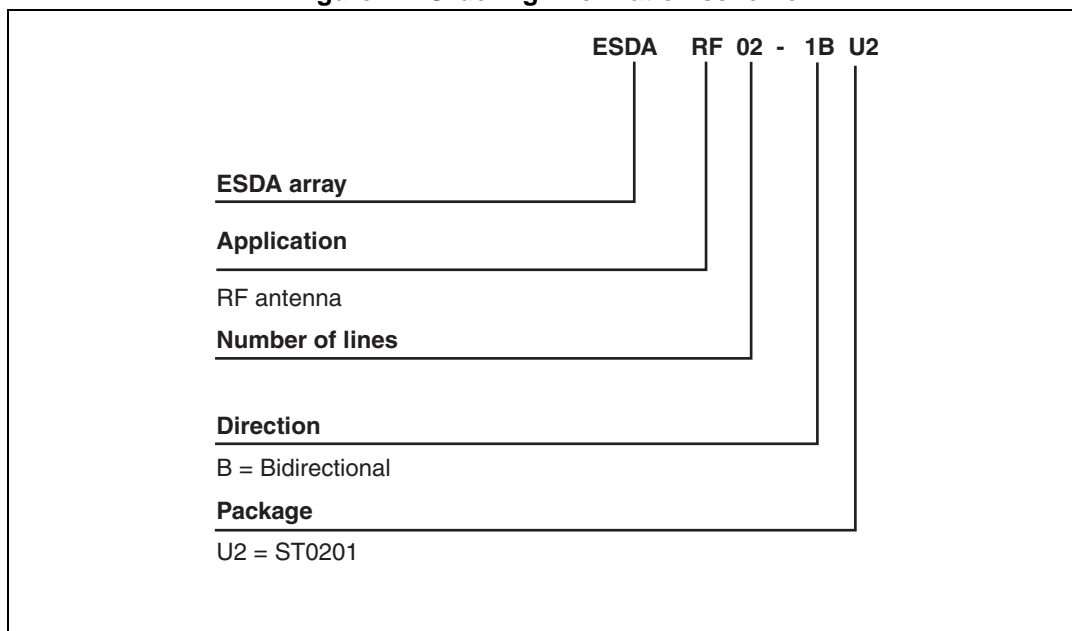


Table 4. Ordering information

Order code	Marking	Weight	Base qty	Delivery mode
ESDARF02-1BU2	Z1 ⁽¹⁾	0.124 mg	15000	Tape and reel

1. The marking can be rotated by 180° to differentiate assembly location

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
22-Jul-2014	1	Initial release.
20-Aug-2015	2	Updated <i>Features</i> and reformatted to current standard.

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